



Printable and Flexible Electronics for Sensors, Volume II

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Deadline for manuscript
submissions:
closed (31 October 2021)

Message from the Guest Editors

Printable and flexible electronic materials have gained a tremendous amount of interest both in academia and in industry, due to their potential impact in many areas including advanced manufacturing, healthcare, diagnostics, wearables, renewable energy, and defense, to name a few. In this Special Issue, we focus on the latest advancements, current challenges, and new opportunities in the world of printable and flexible electronics. We will cover both fundamentals and applications. Fundamentals include novel materials, manufacturing techniques, and characterization, among others. Applications include chemical and biological sensing, point-of-care diagnostics, detection of explosives and nerve agents, foodborne pathogens, environmental monitoring, toxic gas detection, and micro- and nano-actuators, as well as 3D-printed electronics. We will also discuss technological breakthroughs and the latest developments in the formats of both short communications and full papers. The goal of this Special Issue is to stimulate the community by addressing the key issues on the topic in the hope that printable and flexible electronics will make a greater impact in our society.





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Message from the Editor-in-Chief

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